

Docket No. 215207US0PCT
IN RE APPLICATION OF: Hiroshi ORIKABE, et al.
SERIAL NO: 09/926,370
FILED: December 28, 2001
FOR: THERMOSETTING RESIN COMPOSITION AND FLEXIBLE CIRCUIT OVERCOATING MATERIAL
COMPRISING THE SAME



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COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Transmitted herewith is an amendment in the above-identified application.

- No additional fee is required
- Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- Additional documents filed herewith:

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS	RATE	CALCULATIONS
TOTAL	16	MINUS	20	0	x \$18 =	\$0.00
INDEPENDENT	1	MINUS	3	0	x \$84 =	\$0.00
		<input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS			+ \$280 =	\$0.00
						\$0.00
		<input type="checkbox"/> Reduction by 50% for filing by Small Entity				\$0.00
		<input type="checkbox"/> Recordation of Assignment			+ \$40 =	\$0.00
						TOTAL \$0.00

- A check in the amount of \$0.00 is attached.
- Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

THE APPLICATION OF

HIROSHI ORIKABE, ET AL.

: ATTN: APPLICATION DIVISION

SERIAL NO: 09/926,370

:

FILED: DECEMBER 28, 2001

: GROUP ART UNIT: 1755

FOR: THERMOSETTING RESIN
COMPOSITION AND FLEXIBLE
CIRCUIT OVERCOATING
MATERIAL COMPRISING THE
SAME

:

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Prior to examination on the merits, please amend the above-identified application as follows: